



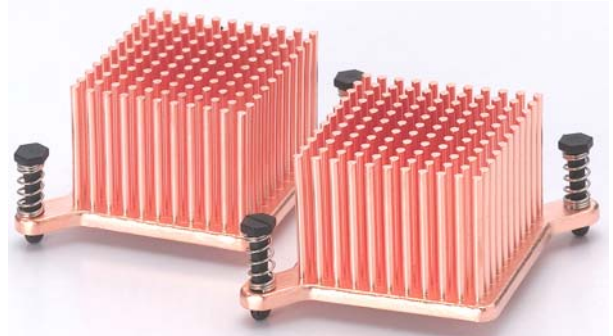
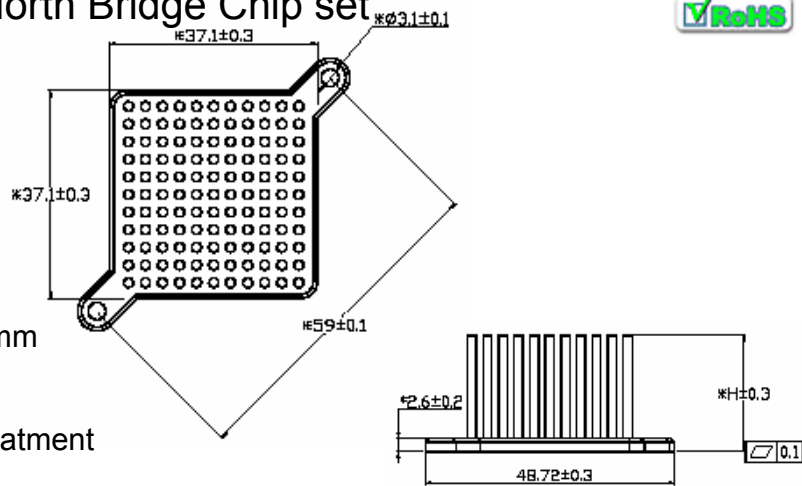
Model : CMBA054949 Series

BGA Heat Sink Specification

For North Bridge Chip set



1. Material : CU1100
2. Dimension :
Foot print : 37.5x37.5mm
Height : 12,15,18,21,23,28,33 mm
Base (thickness) : 2.6mm
3. Finish: Antioxidant Treatment
4. Accessory :
Push Pin : Plastic (UL94-V0)
Thermal pad : T725 or others



Performance

Heat Source (LxW)

15x15

